Features

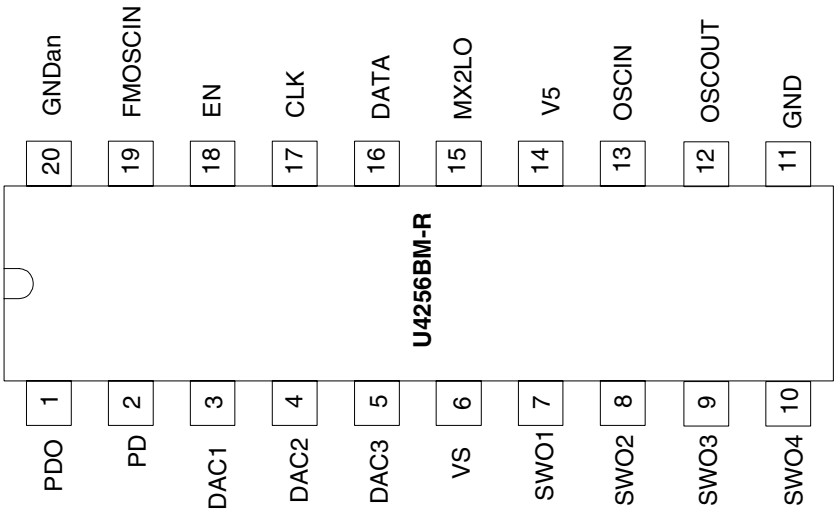
- Reference Oscillator up to 15 MHz (Tuned)
- Oscillator Buffer Output (for AM Up/Down Conversion)
- Two Programmable 16-bit Dividers
- Fine-tuning Steps Possible
- Fast Response Time due to Integrated Loop Push-pull Stage
- 3-wire Bus (Enable, Clock and Data; 3 V and 5 V Microcontrollers Acceptable)
- Four Programmable Switching Outputs (Open Drain)
- Three DACs for Software Controlled Tuner Alignment
- Low-power Consumption
- High S/N Ratio
- Integrated Band Gap – only One Supply Voltage Necessary

Description

The U4256BM-R is a synthesizer IC for FM receivers and an AM up-convertion system in BICMOS technology. Together with the AM/FM IC T4258 or U4255BM, it performs a complete AM/FM car radio front-end, which is recommended also for RDS (Radio Data System) applications. It is controlled by a 3-wire bus and also contains switches and Digital to Analog Converters (DACs) for software-controlled alignment of the AM/FM tuner. The U4256BM-R is the pin-compatible succesor IC of U4256BM-N.

Pin Configuration

Figure 1. Pinning SSO20



Frequency Synthesizer for Radio Tuning

U4256BM-R

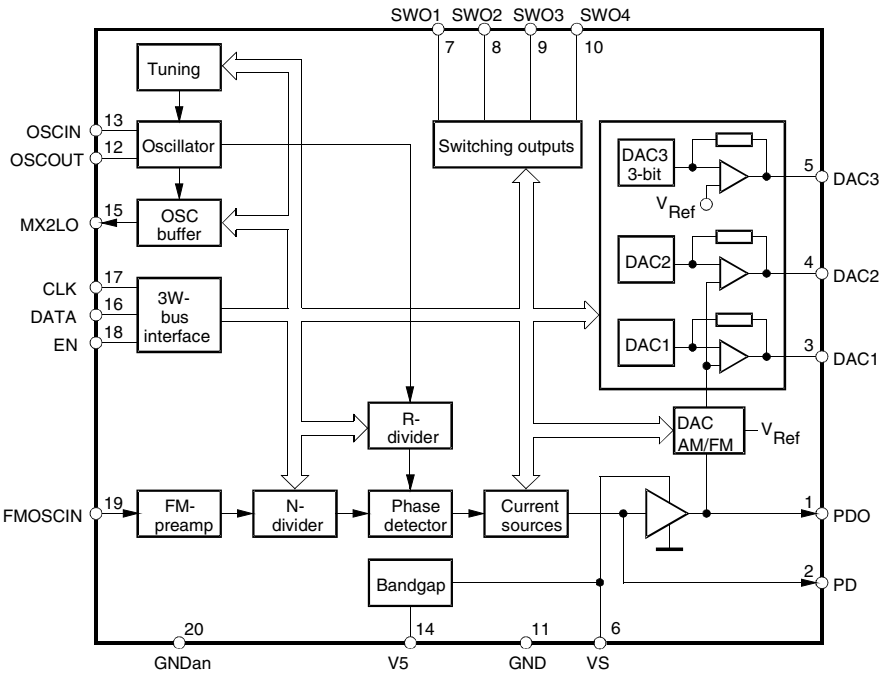
Preliminary

Rev. 4562C–AUDR–08/04

Pin Description

Pin	Symbol	Function
1	PDO	Phase detector output
2	PD	Pulsed current output
3	DAC1	Digital-to-analog converter 1
4	DAC2	Digital-to-analog converter 2
5	DAC3	Digital-to-analog converter 3
6	VS	Supply voltage analog part
7	SWO1	Switching output 1
8	SWO2	Switching output 2
9	SWO3	Switching output 3
10	SWO4	Switching output 4
11	GND	Ground, digital part
12	OSCOUT	Reference oscillator output
13	OSCIN	Reference oscillator input
14	V5	Capacitor band gap
15	MX2LO	Oscillator buffer output
16	DATA	Data input
17	CLK	Clock
18	EN	Enable
19	FMOSCIN	FM-oscillator input
20	GNDan	Ground, analog part

Figure 2. Block Diagram



Functional Description

For a tuned FM-broadcast receiver, the following parts are needed:

- Voltage-Controlled Oscillator (VCO)
- Antenna Amplifier Tuned Circuit
- RF Amplifier Tuned Circuit

Typical modern receivers with electronic tuning are tuned to the desired FM frequency by the frequency synthesizer IC U4256BM-R. The special design allows the user to build software-controlled tuner alignment systems. Two programmable DACs (Digital-to-Analog Converter) support the computer-controlled alignment. The output of the PLL is a tuning voltage which is connected to the VCO of the receiver IC. The output of the VCO is equal to the desired station frequency plus the IF (10.7 MHz). The RF and the oscillator signal (VCO) are both input to the mixer that translates the desired FM channel signal to the fixed IF signal. For FM, the double-conversion system of the receiver requires exactly 10.7 MHz for the first IF frequency, which determines the center frequency of the software-controlled integrated second IF filter.

If this oscillator tuning feature is not used, the internal capacities have to be switched off and the oscillator has to be operated with high-quality external capacities to ensure that the operational frequency is exactly 10.250 MHz.

When dimensioning the oscillator circuit, it is important that the additional capacities enable the oscillator to operate through its complete tracking range. The oscillating ability depends very strongly on the used crystal oscillator. Initializing the oscillator should be established without switching any additional capacities to guarantee that the oscillator starts to operate properly. Due to the lower quality of the integrated capacities compared to discrete capacities, the amount of the switched integrated capacities should always be minimized. (If necessary reduce tracking range or use another crystal oscillator.)

The U4256BM-R has a very fast response time of maximum 800 µs (at 2 mA, f_{Step} = 50 kHz, measured on MPX signal). It performs a high signal to noise ratio. Only one supply voltage is necessary, due to a integrated band gap.

Input/Output Interface Circuits

PDO (Pin 1)

PDO is the buffer amplifier output of the PLL. The bipolar output stage is a rail-to-rail amplifier.

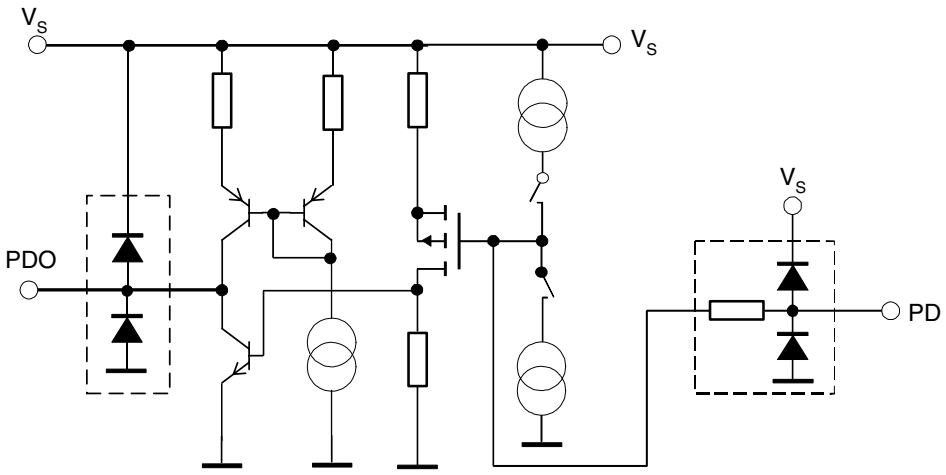
PD (Pin 2)

PD is the current charge pump output of the PLL. The current can be controlled by setting the Bits. The loop filter has to be designed corresponding to the choosen pump current and the internal reference frequency. A recommendation can be found in the application circuit.

The charge-pump current can be choosen by setting the Bits 71 and 70 as following:

IPD (µA)	B71	B70
25	0	0
100	0	1
500	1	0
2000	1	1

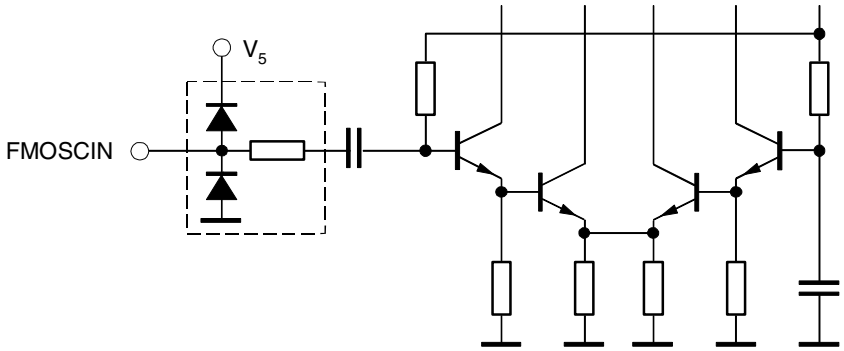
Figure 3. Internal Components at PDO Connection



FMOSCIN (Pin 19)

FMOSCIN is the preamplifier input for the FM oscillator signal.

Figure 4. Internal Components at FMOSCIN



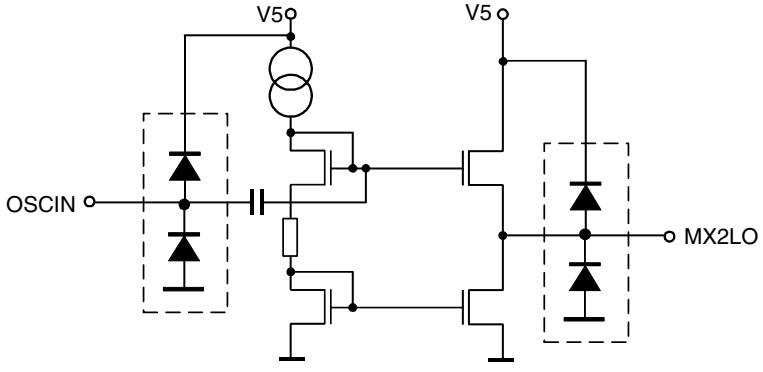
MX2LO (Pin 15)

MX2LO is the buffered output of the crystal oscillator. This signal can be used as a reference frequency for U4255BM or T4258.

The oscillator buffer output can be switched by the OSCB Bit as following (Bit 69)

MX2LO AC Voltage	B69
ON	0
OFF	1

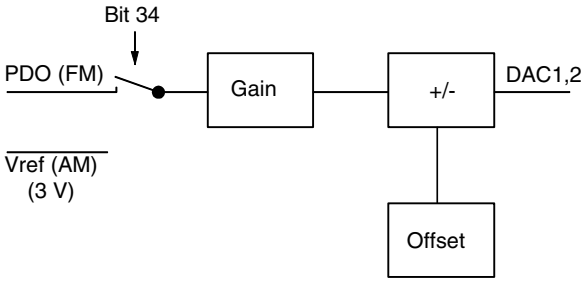
Figure 5. Internal Components at MX2LO



Function of DAC1, 2 in FM and AM Mode (Pin 3 and Pin 4)

For automatic tuner alignment, the DAC1 and DAC2 of the U4256BM-R can be controlled by setting gain of VPDO and offset values. The following figure shows the principle of the operation. In FM Mode the gain is in the range of $0.69 \times V_{(PDO)}$ to $2.16 \times V_{(PDO)}$. The offset range is +0.56 V to -0.59 V. For alignment, DAC1 and DAC2 are connected to the varicaps of the preselection filters. For alignment, offset and gain is set for having the best tuner tracking.

Figure 6. Principle Operation for Alignment

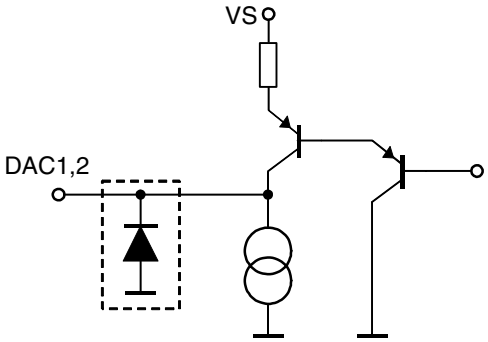


The DAC mode can be controlled by setting the Bit 34 as following:

DAC Mode	B34
FM	0
AM	1

If Bit 34 = 1 (AM Mode), the DAC1, DAC2 can be used as standard DAC converters. The internal voltage of 3 V is connected to the gain- and offset-input of DAC1 and DAC2 (only in AM Mode). The gain is in the range of 0.46×3 V to 3.03×3 V. The offset range is +1.46 V to -1.49 V.

Figure 7. Internal Components at DAC1,2 Output



DAC 1, 2 in FM Mode (Pin 3 and Pin 4)

The gains of DAC1 and DAC2 have a range of $0.69 \times V_{(PDO)}$ to $2.16 \times V_{(PDO)}$. $V_{(PDO)}$ is the PLL tuning voltage output. This range is divided into 256 steps. So one step is approximately $(2.16 - 0.46) \times V_{(PDO)} / 255 = 0.005764 \times V_{(PDO)}$. The gain of DAC1 can be controlled by the Bits 36 to 43 (G-2^0 to G-2^7) and the gain of DAC2 by the Bits 0 to 7 (G-2^0 to G-2^7) as following:

Gain DAC1 Approximately	B43	B42	B41	B40	B39	B38	B37	B36	Decimal Gain
Gain DAC2 Approximately	B7	B6	B5	B4	B3	B2	B1	B0	Decimal Gain
$0.69 \times V_{(PDO)}$	0	0	0	0	0	0	0	0	0
$0.69576 \times V_{(PDO)}$	0	0	0	0	0	0	0	1	1
$0.70153 \times V_{(PDO)}$	0	0	0	0	0	0	1	0	2
$0.70729 \times V_{(PDO)}$	0	0	0	0	0	0	1	1	3
...	...	...	...	...	...	...	...	...	...
$0.99549 \times V_{(PDO)}$	0	0	1	1	0	1	0	1	53
...	...	...	...	...	...	...	...	...	...
$2.14847 \times V_{(PDO)}$	1	1	1	1	1	1	0	1	253
$2.15424 \times V_{(PDO)}$	1	1	1	1	1	1	1	0	254
$2.16 \times V_{(PDO)}$	1	1	1	1	1	1	1	1	255

Offset = 31 (intermediate position)

The offset of DAC1 and DAC2 has a range of 0.56 V to -0.59 V. This range is divided into 64 steps. So one step is approximately 1.15 V/ 63 = 18.25 mV. The offset DAC1 can be controlled by the Bits 44 to 49 (O-2^0 to O-2^5) and the offset of DAC2 by the Bits 8 to 13 (O-2^0 to O-2^5) as following:

Offset DAC1 Approximately	B49	B48	B47	B46	B45	B44	Decimal Gain
Offset DAC2 Approximately	B13	B12	B11	B10	B9	B8	Decimal Gain
0.56 V	0	0	0	0	0	0	0
0.5417 V	0	0	0	0	0	1	1
0.5235 V	0	0	0	0	1	0	2
0.5052 V	0	0	0	0	1	1	3
...	...	...	...	...	...	...	...
+0.0059 V	0	1	1	1	1	1	31
...	...	...	...	...	...	...	...
0.5535 V	1	1	1	1	0	1	61
-0.5717 V	1	1	1	1	1	0	62
-0.59 V	1	1	1	1	1	1	63

Gain = 53 (intermediate position)

DAC 1, 2 in AM Mode (Pin 3 and Pin 4)

In AM mode the DAC input voltage $V_{(PDO)}$ is internal connected to 3 V. The gains of DAC1 and DAC2 have a range of 0.46 × 3 V to 3.03 × 3 V. $V_{(PDO)}$ is the PLL tuning voltage output. This range is divided into 256 steps. So one step is approximately (3.03 - 0.46) × 3 V/255 = 0.01007 × 3 V. The gain of DAC1 can be controlled by the Bits 36 to 43 (G-2^0 to G-2^7) and the gain of DAC2 by the Bits 0 to 7 (G-2^0 to G-2^7) as following:

Gain DAC1 Approximately	B43	B42	B41	B40	B39	B38	B37	B36	Decimal Gain
Gain DAC2 Approximately	B7	B6	B5	B4	B3	B2	B1	B0	Decimal Gain
0.4607 × 3 V	0	0	0	0	0	0	0	0	0
0.4710 × 3 V	0	0	0	0	0	0	0	1	1
0.4812 × 3 V	0	0	0	0	0	0	1	0	2
0.4915 × 3 V	0	0	0	0	0	0	1	1	3
...	...	...	...	...	...	...	...	...	...
1.0029 × 3 V	0	0	1	1	0	1	0	1	53
...	...	...	...	...	...	...	...	...	...
3.0097 × 3 V	1	1	1	1	1	1	0	1	253
3.0196 × 3 V	1	1	1	1	1	1	1	0	254
3.0296 × 3 V	1	1	1	1	1	1	1	1	255

Offset = 31 (intermediate position)

Remark: $V_{(PDO)}$ is 3 V in AM mode.

The offset of DAC1 and DAC2 has a range of +1.46 V to -1.49 V. This range is divided into 64 steps. So one step is approximately 2.95 V/ 63 = 46.8 mV. The offset DAC1 can be controlled by the Bits 44 to 49 (O-2^0 to O-2^5) and the offset of DAC2 by the Bits 8 to 13 (O-2^0 to O-2^5) as following:

Offset DAC1 Approximately	B49	B48	B47	B46	B45	B44	Decimal Gain
Offset DAC2 Approximately	B13	B12	B11	B10	B9	B8	Decimal Gain
1.4606 V	0	0	0	0	0	0	0
1.4138 V	0	0	0	0	0	1	1
1.3665 V	0	0	0	0	1	0	2
1.3196 V	0	0	0	0	1	1	3
...	...	...	...	...	...	...	...
-0.0079 V	0	1	1	1	1	1	31
...	...	...	...	...	...	...	...
-1.3975 V	1	1	1	1	0	1	61
-1.4447 V	1	1	1	1	1	0	62
-1.4917 V	1	1	1	1	1	1	63

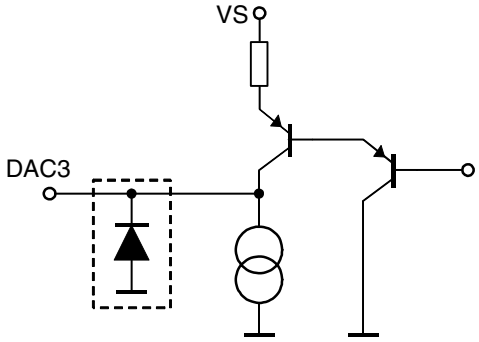
Gain = 53 (intermediate position)

DAC3 (Pin 5)

The DAC3 output voltage can be controlled by the Bits P-2^0 to P-2^2 (Bits 66 to 68) as following:

DAC3 Offset Approximately	B68	B67	B66
0.55 V	0	0	0
1.25 V	0	0	1
1.90 V	0	1	0
2.60 V	0	1	1
3.30 V	1	0	0
4.10 V	1	0	1
4.80 V	1	1	0
5.45 V	1	1	1

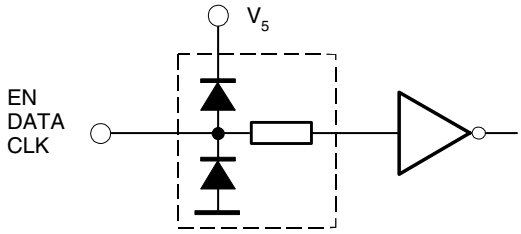
Figure 8. Internal Components at DAC3



EN, DATA, CLK (Pin 16-18)

All functions can be controlled via a 3-wire bus consisting of ENABLE, DATA and CLOCK. The bus is designed for microcontrollers which operate with 3 V supply voltage. Details of the data transfer protocol are shown in the table ‘3-wire Bus Description’.

Figure 9. Internal Components at EN, DATA, CLK



SWO1, 2, 3 and 4 (Pin 7-10)

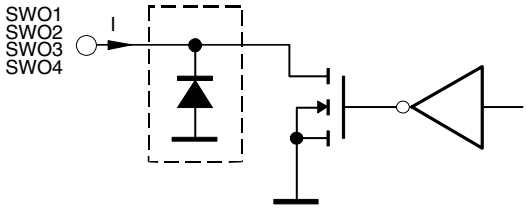
All switching outputs are ‘open drain’ and can be set and reset by software control. Details are described in the data transfer protocol.

The switching output SWO1 to SWO4 can be controlled as following (Bits 30 to 33):

Switch Output	B30 + X
SWOx = ON (switch to GND)	0
SWOx = OFF	1

X = 0 to 3

Figure 10. Internal Components at SWO1, 2, 3 and 4



OSCIN, OSCOUT (Pin 12 and Pin 13)

A crystal resonator (up to 15 MHz) is connected between OSCIN and OSCOUT in order to generate the reference frequency. By using the U4256BM-R in connection with U4255BM or T4258, the crystal frequency must be 10.25 MHz. The complete application circuit is shown in Figure 15. If a reference is available, it can be applied at OSCIN. The minimum voltage should be 100 mVrms. In this case, Pin OSCOUT has to be open.

The tuning capacity for the crystal oscillator has a range of 0.5 pF to 71.5 pF. The values are coded binary. The tuning can be controlled by the Bits 78 to 85 as following:

B85 = 1 [pF]	B85 = 0 [pF]	B84	B83	B82	B81	B80	B79	B78
0	8.0	1	1	1	1	1	1	1
0.5	8.5	1	1	1	1	1	1	0
1.0	9.0	1	1	1	1	1	0	1
1.5	19.5	1	1	1	1	1	0	0
...	...	...	...	...	...	...	...	...
63.0	71.0	0	0	0	0	0	0	0
63.5	71.5	0	0	0	0	0	0	0

Figure 11. Internal Components at OSCIN and OSCOUT

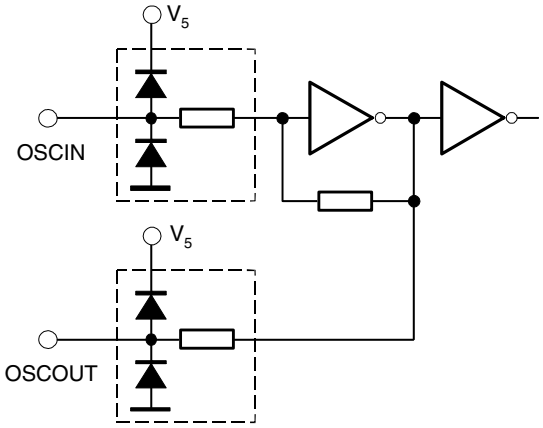
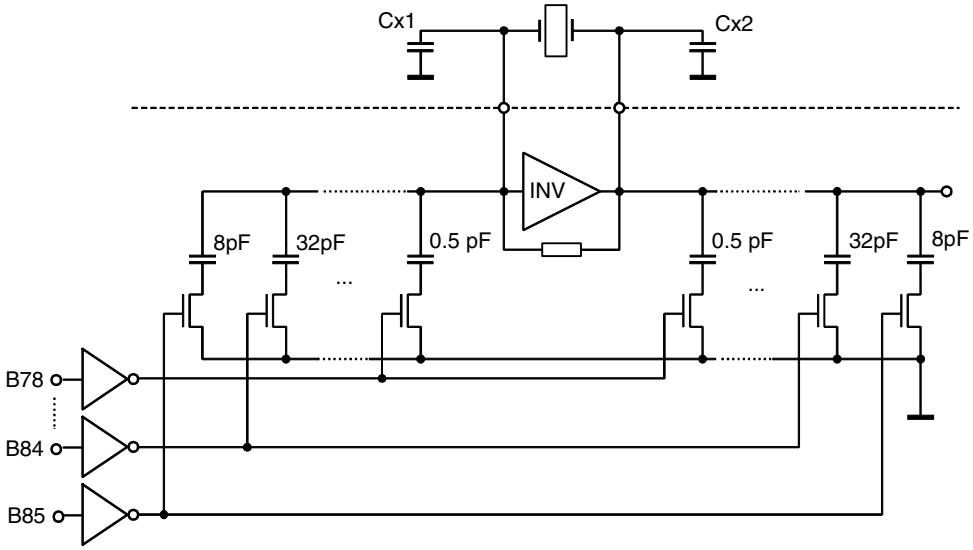
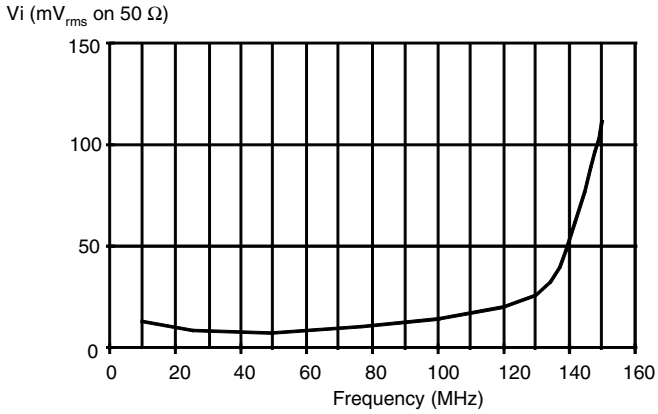


Figure 12. Internal Connection of Tuning Capacity for Crystal Oscillator



Application Information

Figure 13. FMOSCIN Sensitivity



3-wire Bus Description

The register settings of U4256BM-R are programmed by a 3-wire bus protocol. The bus protocol consists of separate commands. A defined number of bits is transmitted sequentially during each command.

One command is used to program all the bits of one register. The different registers available (see table Data Transfer) are addressed by the length of the command (number of transmitted bits) and by two address bits, that are unique to each register of a given length. 16-bit registers are programmed by 16-bit commands and 24-bit registers are programmed by 24-bit commands.

Each bus command starts with a rising edge on the enable line (EN) and ends with a falling edge on EN. EN has to be kept HIGH during the bus command.

The sequence of transmitted bits during one command starts with the LSB of the first byte and ends with the MSB of the last byte of the register addressed. To transmit one bit (0/1) DATA has to be set to the appropriate value (LOW/HIGH) and a LOW to HIGH transition has to be performed on the clock line (CLK) while DATA is valid. The DATA is evaluated at the rising edges of CLK. The number of LOW to HIGH transitions on CLK during the HIGH period of EN is used to determine the length of the command.

The bus protocol and the register addressing of U4256BM-R are compatible to the addressing used in U4255BM and T4258. That means U4256BM-R and U4255BM (or T4258) can be operated on the same 3-wire bus as shown in the application circuit.

Figure 14. 3-wire Bus Timing Diagram

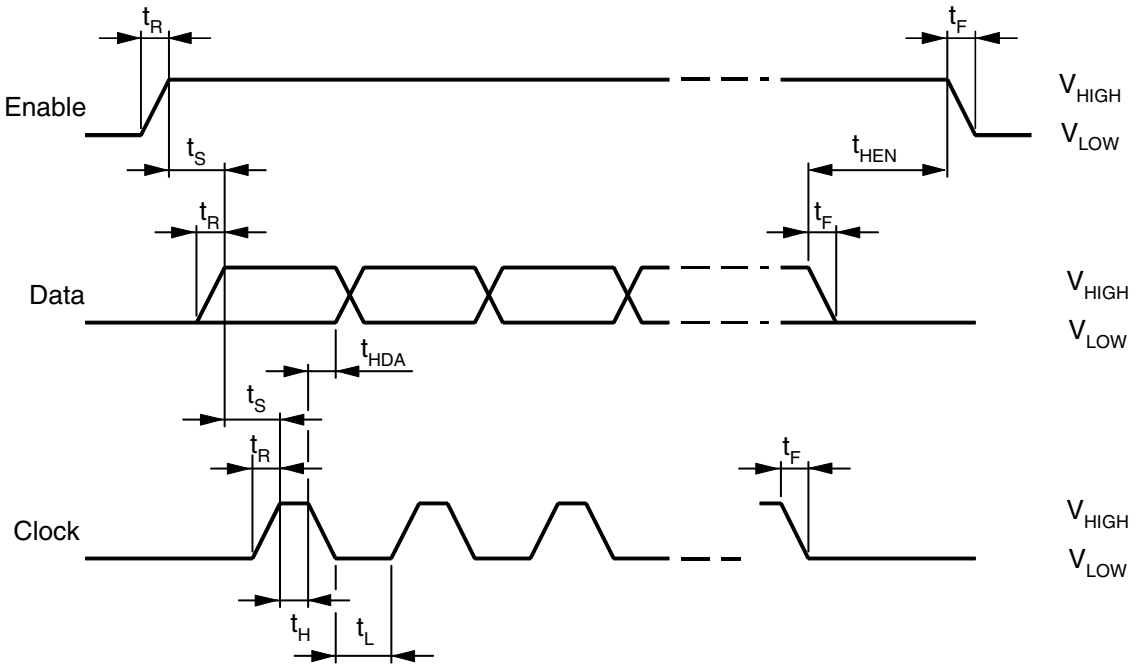
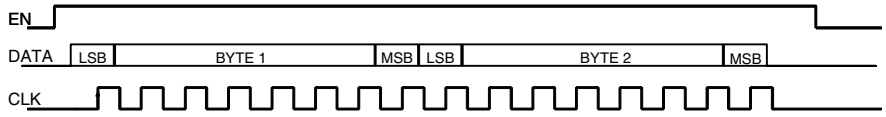
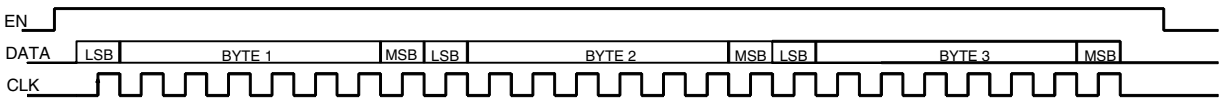


Figure 15. 3-wire Pulse Diagram

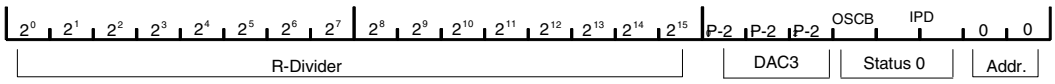
16-bit command



24-bit command



e.g. R-Divider



Data Transfer

Table 1. Control Registers

A																								
MSB		BYTE 3					LSB	MSB	BYTE 2							LSB	MSB	BYTE 1						LSB
ADDR.		STATUS 0			DAC3			R-Divider																
0	0	IPD		OSCB 0=on, 1=off	P-2^2	P-2^1	P-2^0	2^{15}	2^{14}	2^{13}	2^{12}	2^{10}	2^{11}	2^9	2^8	2^7	2^6	2^5	2^4	2^3	2^2	2^1	2^0
		B71	B70	B69	B68	B67	B66	B65	B64	B63	B62	B61	B60	B59	B58	B57	B56	B55	B54	B53	B52	B51	B50

B																								
MSB		BYTE 3					LSB	MSB	BYTE 2							LSB	MSB	BYTE 1						LSB
ADDR.		STATUS 1						N-Divider																
0	1	0	AM=1 FM=0 DAC	SWO4 0=on, 1=off	SWO3 0=on, 1=off	SWO2 0=on, 1=off	SWO1 0=on, 1=off	2^{15}	2^{14}	2^{13}	2^{12}	2^{10}	2^{11}	2^9	2^8	2^7	2^6	2^5	2^4	2^3	2^2	2^1	2^0
		B35	B34	B33	B32	B31	B30	B29	B28	B27	B26	B25	B24	B23	B22	B21	B20	B19	B18	B17	B16	B15	B14

C															
MSB		BYTE 2					LSB	MSB	BYTE 1						LSB
ADDR.		DAC1 OFFSET						DAC1 GAIN							
0	0	O-2^5	O-2^4	O-2^3	O-2^2	O-2^1	O-2^0	G-2^7	G-2^6	G-2^7	G-2^5	G-2^4	G-2^3	G-2^2	G-2^0
		B49	B48	B47	B46	B45	B44	B43	B42	B41	B40	B39	B38	B37	B36

D															
MSB		BYTE 2					LSB	MSB	BYTE 1						LSB
ADDR.		DAC2 OFFSET						DAC2 GAIN							
0	1	O-2^5	O-2^4	O-2^3	O-2^2	O-2^1	O-2^0	G-2^7	G-2^6	G-2^7	G-2^5	G-2^4	G-2^3	G-2^2	G-2^0
		B13	B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2	B1	B0

E															
MSB		BYTE 2					LSB	MSB	BYTE 1						LSB
ADDR.		Oscillator tuning function							Not used						
1	0	8pF	32pF	16pF	8pF	4pF	2pF	1pF	0.5pF	X	X	X	X	X	X
		B85	B84	B83	B82	B81	B80	B79	B78	B77	B76	B75	B74	B73	B72

Absolute Maximum Ratings

Parameters		Symbol	Value	Unit
Analog supply voltage	Pin 6	V_S	8 to 12	V
Input voltage BUS	Pins 16, 17 and 18	V_I	-0.3 to +5.3	V
Output current switches (see Figure 10)	Pins 7, 8, 9 and 10	I_O	-1 to +5	mA
Drain voltage switches	Pins 7, 8, 9 and 10	V_{OD}	15	V
Ambient temperature range		T_{amb}	-40 to +85	°C
Storage temperature range		T_{stg}	-40 to +125	°C
Junction temperature		T_j	125	°C
Electrostatic handling M.M.		V_{ESD}	300	V

Thermal Resistance

Parameters	Symbol	Value	Unit
Junction ambient, when soldering to PCB	R_{thJA}	140	K/W

Operating Range

All voltages are referred to GND (Pin 11)

Parameters		Symbol	Min.	Typ.	Max.	Unit
Supply voltage range	Pin 6	V_S	8	8.5	12	V
Ambient temperature		T_{amb}	-40		+85	°C
Input frequency FMOSCIN	Pin 19	f_{in}	70		160	MHz
Programmable N, R divider		SF	2		65535	
Crystal reference oscillator	Pins 12 and 13	fXTAL	0.1		15	MHz

Electrical Characteristics

Test Conditions (unless otherwise specified): V_S = 8.5 V, T_{amb} = 25°C.

No.	Parameters	Test Conditions	Pin	Symbol	Min.	Typ.	Max.	Unit	Type*
1	**Supply Voltage**								
1.1	Analog supply voltage		6	V_S	8	8.5	12	V	A
2	**Supply Current**								
2.1	Analog supply current		6	I_S	5	10	25	mA	A
3	**OSCIN**								
3.1	Input voltage	f = 0.1 to 15 MHz	13	OSC	100			mV_{rms}	B
4	**OSC Buffer (MX2LO)**								
4.1	Output AC voltage	At Pin15: 47 pF and 1 kΩ	15	v_{MX2LO}	80	120	200	mV_{pp}	B
4.2	Output DC voltage		15	V_{MX2LO}	1.8	2.0	2.2	V	A
5	**FMOSCIN**								
5.1	Input voltage	f = 70 to 120 MHz f = 120 to 160 MHz	19	FMOSC FMOSC	40 150			mV_{rms} mV_{rms}	B
6	**Pulsed Current Output PD**								
6.1	Output current Bit 71, 70 = ‘00’	PD = 2.5 V	2	±IPD	20	25	30	µA	A
6.2	Output current Bit 71, 70 = ‘01’	PD = 2.5 V	2	±IPD	80	100	120	µA	A
6.3	Output current Bit 71, 70 = ‘10’	PD = 2.5 V	2	±IPD	400	500	600	µA	A
6.4	Output current Bit 71, 70 = ‘11’	PD = 2.5 V	2	±IPD	1500	2000	2400	µA	A
6.5	Leakage current	PD = 2.5 V	2	±IPDL			20	nA	A

*) Type means: A = 100% tested, B = 100% correlation tested, C = Characterized on samples, D = Design parameter

Electrical Characteristics (Continued)

Test Conditions (unless otherwise specified): V_S = 8.5 V, T_{amb} = 25°C.

No.	Parameters	Test Conditions	Pin	Symbol	Min.	Typ.	Max.	Unit	Type*
7	**PDO**								
7.1	Saturation voltage HIGH		3, 4		8.0		8.5	V	A
7.2	Saturation voltage LOW		3, 4		0		0.4	V	A
8	**SWO1, SWO2, SWO3, SWO4 (Open Drain)**								
8.1	Output leakage current HIGH	Pin 7,8,9,10 over R against 8.5 V	7, 8, 9, 10	I_{SWOH}			100	nA	A
8.2	Output voltage LOW	I = 1 mA	7, 8, 9, 10	V_{SWOL}		100	400	mV	A
9	**DAC1, DAC2**								
9.1	Output current		3, 4	$I_{DAC1, 2}$			±1	mA	C
9.2	Output voltage		3, 4	$V_{DAC1, 2}$	0.3		V_S-0.6	V	A
9.3	Maximum offset range (FM)	offset = 0, gain = 53	3, 4		0.45	0.56	0.65	V	A
9.4	Minimum offset range (FM)	offset = 63, gain = 53	3, 4		-0.45	-0.57	-0.65	V	A
9.5	Maximum gain range (FM)	gain = 255, offset = 31	3, 4		0.63	0.69	0.75		A
9.6	Minimum gain range (FM)	gain = 0, offset = 31	3, 4		2.1	2.16	2.23		A
10	**DAC3**								
10.1	Output current		5	I_{DAC3}			±1	mA	C
10.2	Output voltage	Bit 68-66: 000	5	V_{DAC3}	0.4	0.55	0.7	V	A
10.3	Output voltage	Bit 68-66: 001	5	V_{DAC3}	1.1	1.25	1.4	V	A
10.4	Output voltage	Bit 68-66: 010	5	V_{DAC3}	1.8	1.90	2.1	V	A
10.5	Output voltage	Bit 68-66: 011	5	V_{DAC3}	2.4	2.60	2.8	V	A
10.6	Output voltage	Bit 68-66: 100	5	V_{DAC3}	3.2	3.30	3.5	V	A
10.7	Output voltage	Bit 68-66: 101	5	V_{DAC3}	3.8	4.10	4.3	V	A
10.8	Output voltage	Bit 68-66: 110	5	V_{DAC3}	4.5	4.80	5.0	V	A
10.9	Output voltage	Bit 68-66: 111	5	V_{DAC3}	5.2	5.45	5.7	V	A
11	**3-wire Bus, ENABLE, DATA, CLOCK**								
11.1	Input voltage HIGH LOW		16-18	V_{BUSH} V_{BUSL}	2.7 -0.3		5.3 0.8	V V	A
11.2	Clock frequency		17				1.0	MHz	A
11.3	Period of CLK HIGH LOW		17	t_H t_L	250 250			ns ns	D
11.4	Rise time EN, DATA, CLK		16-18	t_r			400	ns	D
11.5	Fall time EN, DATA, CLK		16-18	t_f			100	ns	D

*) Type means: A = 100% tested, B = 100% correlation tested, C = Characterized on samples, D = Design parameter

Electrical Characteristics (Continued)

Test Conditions (unless otherwise specified): V_S = 8.5 V, T_{amb} = 25°C.

No.	Parameters	Test Conditions	Pin	Symbol	Min.	Typ.	Max.	Unit	Type*
11.6	Set-up time		16-18	t_s	100			ns	D
11.7	Hold time EN		18	t_{HEN}	250			ns	D
11.8	Hold time DATA		16	t_{HDA}	0			ns	D

*) Type means: A = 100% tested, B = 100% correlation tested, C = Characterized on samples, D = Design parameter

Figure 16. Application Circuit

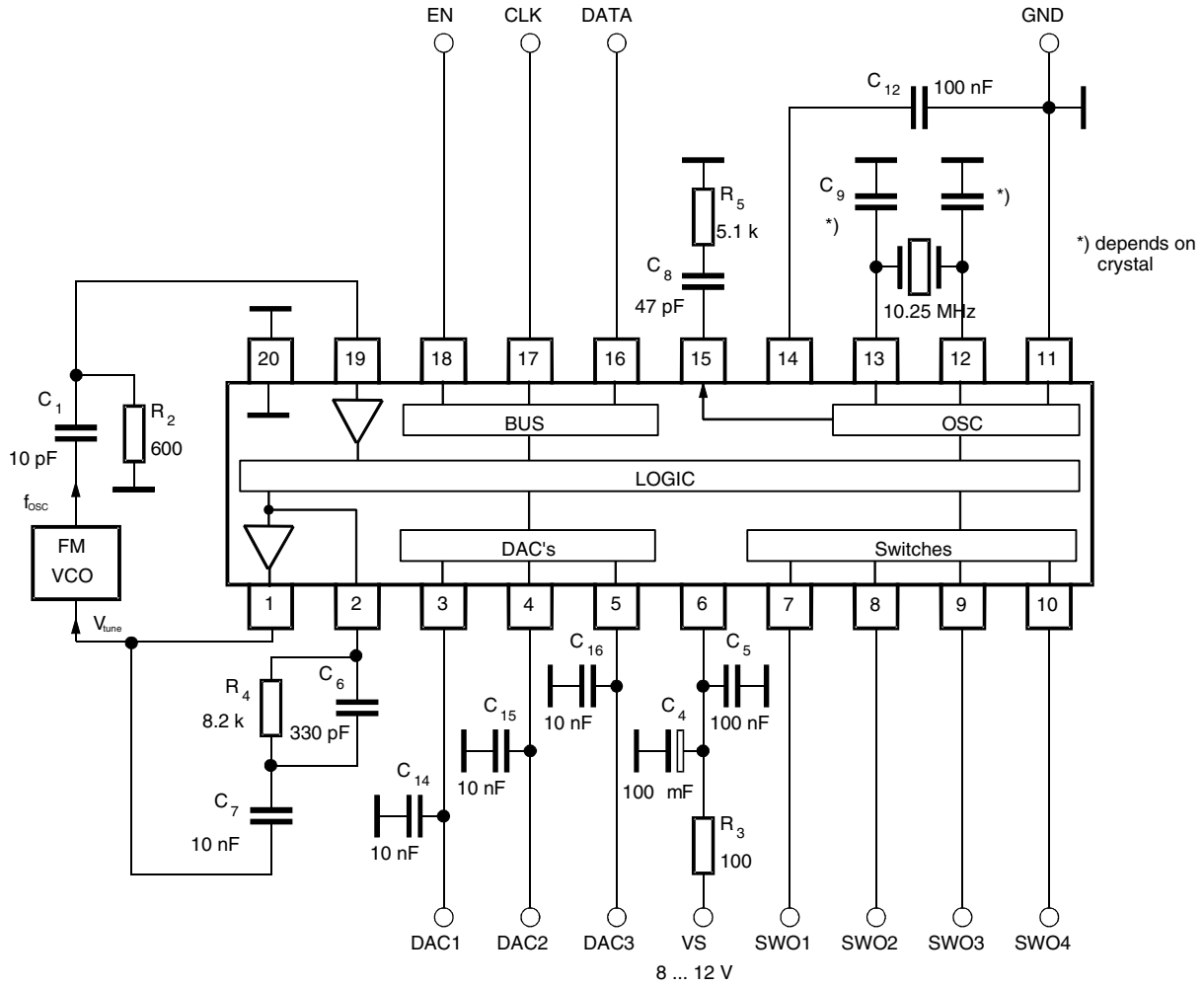
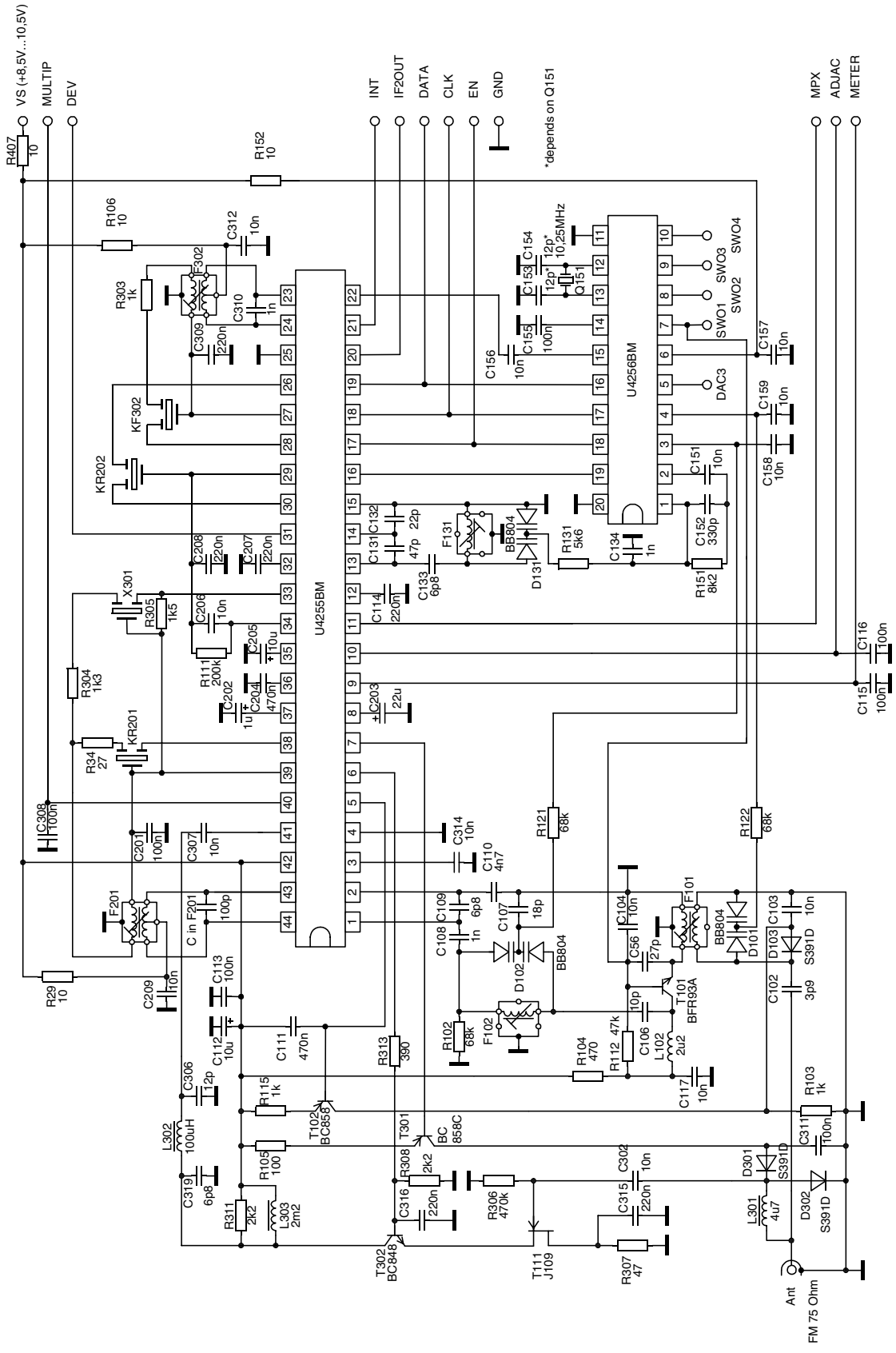


Figure 17. Application Board Schematic

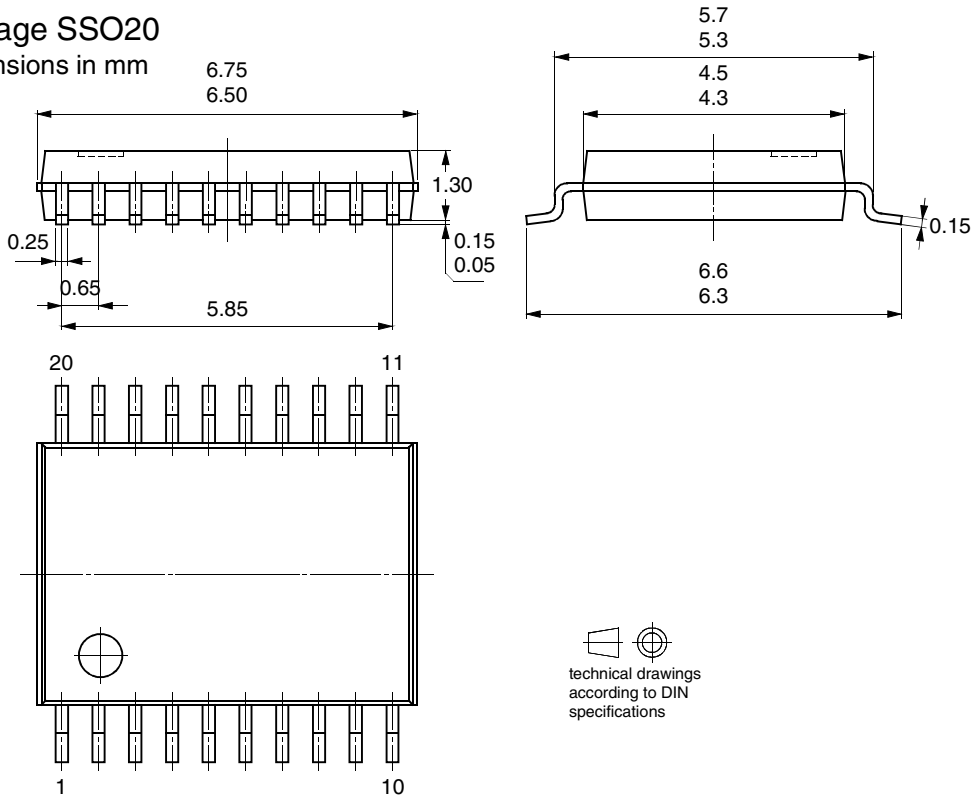


Ordering Information

Extended Type Number	Package	Remarks
U4256BM-RFS	SSO20	Tube
U4256BM-RSG3	SSO20	Taped and reeled

Package Information

Package SSO20
Dimensions in mm



technical drawings
according to DIN
specifications

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